

Title (en)  
DEVICE FOR LASER CUTTING PREPARATIONS, AND A MICROSCOPE

Title (de)  
VORRICHTUNG ZUM LASERSCHNEIDEN VON PRÄPARATEN UND MIKROSKOP

Title (fr)  
DISPOSITIF DE DECOUPAGE LASER DE PREPARATIONS, ET MICROSCOPE

Publication  
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Application  
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Abstract (en)  
[origin: WO0179911A1] The invention relates to a device for laser cutting preparations which comprises an XY table (2) that defines a table surface (4). A holding device (14) for accommodating an object support (6) with a preparation (8) is arranged above the table surface (4) and is joined to the XY table (2) in a manner that permits it to be displaced in the Y direction (20a) in the X direction (22a). An open working space (16) is defined between the holding device (14) and the table surface (4). A catching device (10), which has at least one receptacle (12) for catching a preparation part that has been cut out, can be introduced into said working space. The invention also relates to a microscope that is equipped with the aforementioned laser cutting device.

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